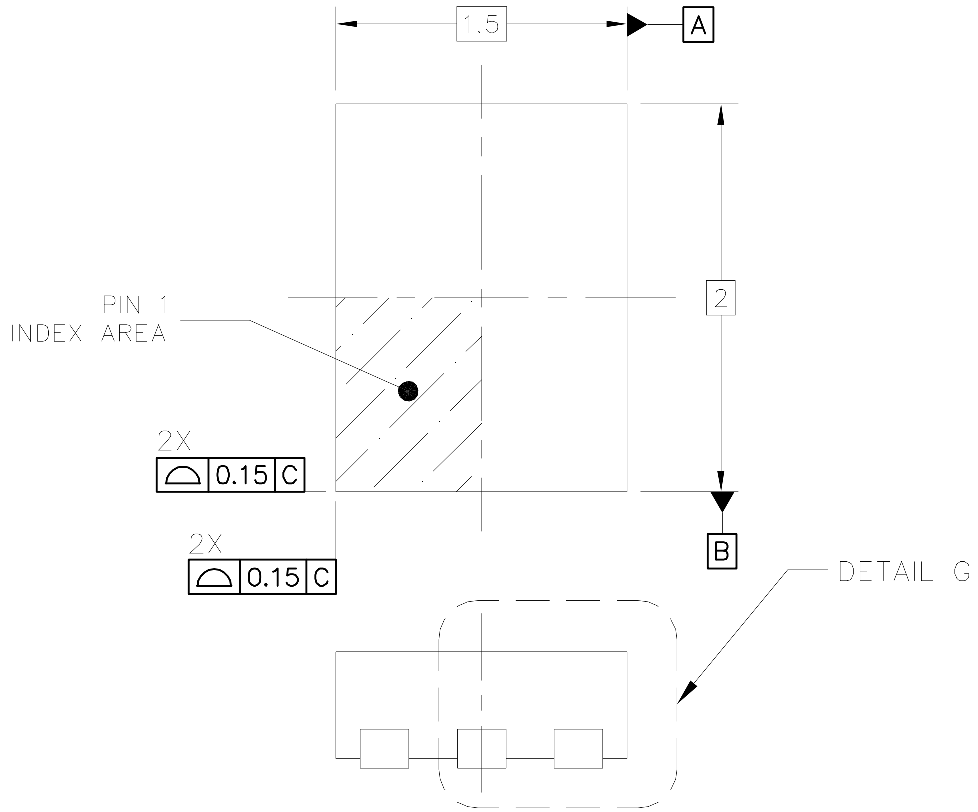


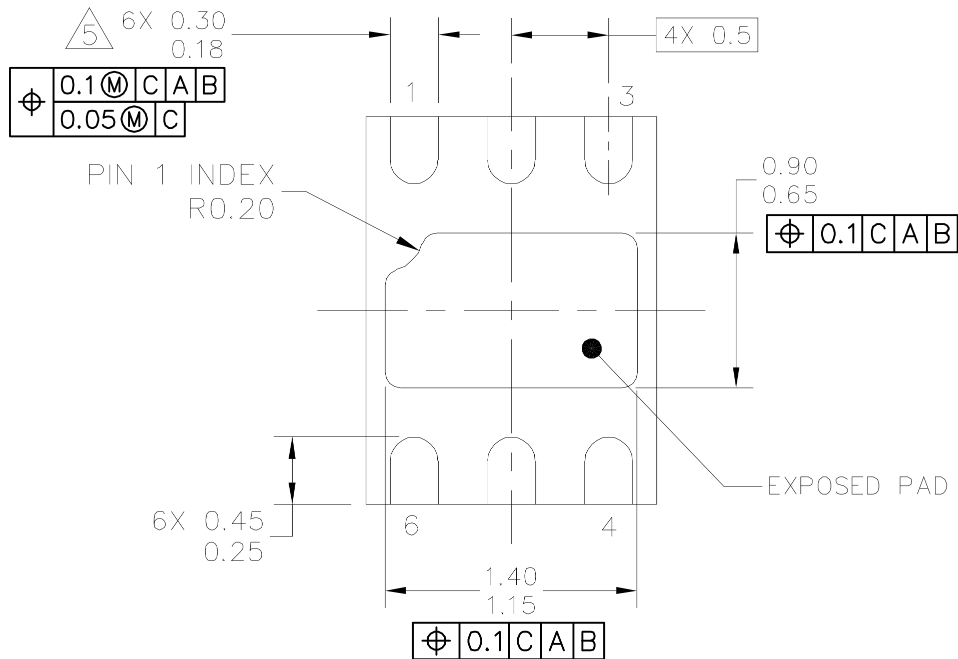


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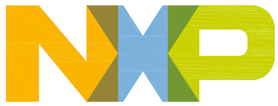
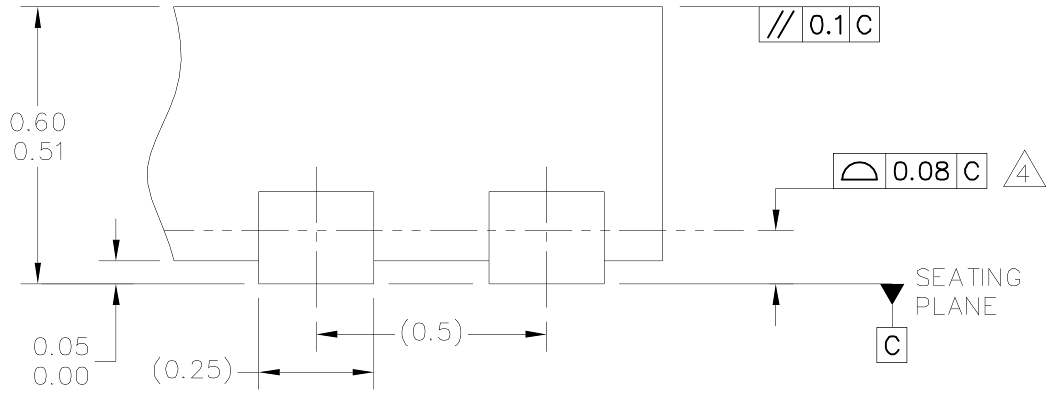
|---|---|---|
| TITLE: THERMALLY ENHANCED DUAL FLAT NON-LEADED PACKAGE (UDFN) 6 TERMINAL, 0.5 PITCH (1.5 X 2 X 0.6) | DOCUMENT NO: 98ASA00224D | REV: A |
| | STANDARD: NON-JEDEC | |
| | SOT1588-1 | 06 JAN 2016 |






DETAIL G

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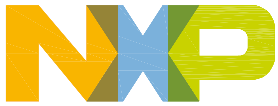

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. THIS IS NON JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO THE TERMINALS AND ALL OTHER BOTTOM SURFACE METALLIZATION.

5. THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURE BETWEEN 0.15 AND 0.25 FROM THE TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THIS DIMENSION SHALL NOT BE MEASURED IN THE RADIUS AREA.

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| --- | --- | --- |
| TITLE: THERMALLY ENHANCED DUAL FLAT NON-LEADED PACKAGE (UDFN) 6 TERMINAL, 0.5 PITCH (1.5 X 2 X 0.6) | DOCUMENT NO: 98ASA00224D | REV: A |
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